



Material Content Data Sheet



Sales Product Name		IPD082N10N3 G		Issued		16. August 2018		
MA#		MA001662900						
Package		PG-TO252-3-313		Weight*		320.18 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	4.609	1.44	1.44	14395	14395
leadframe	inorganic material	phosphorus	7723-14-0	0.044	0.01		138	
	non noble metal	iron	7439-89-6	0.147	0.05		460	
	non noble metal	copper	7440-50-8	147.096	45.93	45.99	459410	460008
	non noble metal	aluminium	7429-90-5	3.987	1.25	1.25	12451	12451
wire	non noble metal	aluminium	7429-90-5	3.987	1.25	1.25	12451	12451
encapsulation	organic material	carbon black	1333-86-4	1.361	0.43		4252	
	plastics	epoxy resin	-	23.822	7.44		74402	
	inorganic material	silicondioxide	60676-86-0	110.944	34.65	42.52	346501	425155
leadfinish	non noble metal	tin	7440-31-5	3.740	1.17	1.17	11681	11681
plating	inorganic material	phosphorus	7723-14-0	0.003	0.00		11	
	non noble metal	nickel	7440-02-0	1.421	0.44	0.44	4437	4448
solder	non noble metal	tin	7440-31-5	0.076	0.02		238	
	noble metal	silver	7440-22-4	0.095	0.03		297	
	non noble metal	lead	7439-92-1	3.635	1.14	1.19	11354	11889
heatspreader	inorganic material	phosphorus	7723-14-0	0.006	0.00		18	
	non noble metal	iron	7439-89-6	0.019	0.01		60	
	non noble metal	copper	7440-50-8	19.177	5.99	6.00	59895	59973
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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